

March 1999 Revised June 2005

74LVT162244 • 74LVTH162244 Low Voltage 16-Bit Buffer/Line Driver with 3-STATE Outputs and 25Ω Series Resistors in the Outputs

General Description

The LVT162244 and LVTH162244 contain sixteen non-inverting buffers with 3-STATE outputs designed to be employed as a memory and address driver, clock driver, or bus oriented transmitter/receiver. The device is nibble controlled. Individual 3-STATE control inputs can be shorted together for 8-bit or 16-bit operation.

The LVT162244 and LVTH162244 are designed with equivalent 25Ω series resistance in both the HIGH and LOW states of the output. This design reduces line noise in applications such as memory address drivers, clock drivers, and bus transceivers/transmitters.

The LVTH162244 data inputs include bushold, eliminating the need for external pull-up resistors to hold unused inputs

These buffers and line drivers are designed for low-voltage (3.3V) V_{CC} applications, but with the capability to provide a TTL interface to a 5V environment. The LVT162244 and LVTH162244 are fabricated with an advanced BiCMOS technology to achieve high speed operation similar to 5V ABT while maintaining a low power dissipation.

Features

- \blacksquare Input and output interface capability to systems at 5V V_{CC}
- Bushold data inputs eliminate the need for external pullup resistors to hold unused inputs (74LVTH162244), also available without bushold feature (74LVT162244).
- Live insertion/extraction permitted
- Power Up/Power Down high impedance provides glitchfree bus loading
- \blacksquare Outputs include equivalent series resistance of 25Ω to make external termination resistors unnecessary and reduce overshoot and undershoot
- Functionally compatible with the 74 series 162244
- Latch-up performance exceeds 500 mA
- ESD performance:

Human-body model > 2000V

Machine model > 200V

Charged-device > 1000V

Also packaged in plastic Fine-Pitch Ball Grid Array (FBGA)

Ordering Code:

Order Number	Package Number	Package Description
74LVT162244G (Note 1)(Note 2)	BGA54A	54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide
74LVT162244MEA (Note 2)	MS48A	48-Lead Small Shrink Outline Package (SSOP), JEDEC MO-118, 0.300" Wide
74LVT162244MTD (Note 2)	MTD48	48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide
74LVTH162244G (Note 1)(Note 2)	BGA54A	54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide
74LVTH162244MEA	MS48A	48-Lead Small Shrink Outline Package (SSOP), JEDEC MO-118, 0.300" Wide [Tube]
74LVTH162244MEX	MS48A	48-Lead Small Shrink Outline Package (SSOP), JEDEC MO-118, 0.300" Wide [Tape and Reel]
74LVTH162244MTD	MTD48	48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide [Tube]
74LVTH162244MTX	MTD48	48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide [Tape and Reel]

Note 1: Ordering code "G" indicates Trays

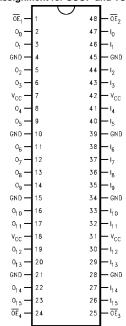
Note 2: Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code

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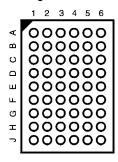
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Connection Diagrams

Pin Assignment for SSOP and TSSOP



Pin Assignment for FBGA



(Top Thru View)

Pin Descriptions

Pin Names	Description
OE _n	Output Enable Inputs (Active LOW)
I ₀ -I ₁₅	Inputs
I ₀ -I ₁₅ O ₀ -O ₁₅	Outputs
NC	No Connect

FBGA Pin Assignments

	1	2	3	4	5	6
Α	O ₀	NC	OE ₁	OE ₂	NC	I ₀
В	02	O ₁	NC	NC	I ₁	l ₂
С	O ₄	O ₃	V _{CC}	V _{CC}	l ₃	I ₄
D	O ₆	O ₅	GND	GND	I ₅	I ₆
E	Ο ₈	07	GND	GND	I ₇	I ₈
F	O ₁₀	O ₉	GND	GND	l ₉	I ₁₀
G	O ₁₂	O ₁₁	V _{CC}	V _{CC}	I ₁₁	I ₁₂
Н	O ₁₄	O ₁₃	NC	NC	I ₁₃	I ₁₄
J	O ₁₅	NC	OE ₄	OE ₃	NC	I ₁₅

Truth Table

Inpu	ts	Outputs
ŌE ₁	I ₀ -I ₃	0 ₀ -0 ₃
L	L	L
L	Н	Н
Н	X	Z
OE ₂	I ₄ –I ₇	O ₄ -O ₇
L	L	L
L	Н	Н
Н	X	Z
ŌE ₃	I ₈ –I ₁₁	O ₈ -O ₁₁
L	L	L
L	Н	Н
Н	X	Z
ŌE₄	I ₁₂ -I ₁₅	O ₁₂ -O ₁₅
L	L	L
L	Н	Н
Н	Х	Z
H - HIGH Voltage Level	I - I OW Voltage I	evel

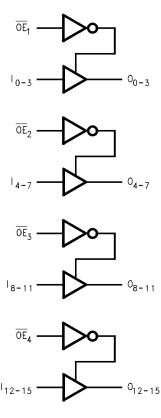
H = HIGH Voltage Level Z = High Impedance

L = LOW Voltage Level X = Immaterial

Functional Description

The LVT162244 and LVTH162244 contain sixteen non-inverting buffers with 3-STATE outputs. The device is nibble (4 bits) controlled with each nibble functioning identically, but independent of the other. The control pins can be shorted together to obtain full 16-bit operation.

Logic Diagram



Absolute Maximum Ratings (Note 3)

Symbol	Parameter	Value	Conditions	Units
V _{CC}	Supply Voltage	-0.5 to +4.6		V
VI	DC Input Voltage	-0.5 to +7.0		V
Vo	Output Voltage	-0.5 to +7.0	Output in 3-STATE	V
		-0.5 to +7.0	Output in HIGH or LOW State (Note 4)	v
I _{IK}	DC Input Diode Current	-50	V _I < GND	mA
I _{OK}	DC Output Diode Current	-50	V _O < GND	mA
I _O	DC Output Current	64	V _O > V _{CC} Output at HIGH State	mA
		128	V _O > V _{CC} Output at LOW State	IIIA
I _{CC}	DC Supply Current per Supply Pin	±64		mA
I _{GND}	DC Ground Current per Ground Pin	±128		mA
T _{STG}	Storage Temperature	-65 to +150		°C

Recommended Operating Conditions

Symbol	Parameter	Min	Max	Units
V _{CC}	Supply Voltage	2.7	3.6	V
VI	Input Voltage	0	5.5	V
I _{OH}	HIGH-Level Output Current		-12	mA
I _{OL}	LOW-Level Output Current		12	mA
T _A	Free Air Operating Temperature	-40	+85	°C
$\Delta t/\Delta V$	Input Edge Rate, V _{IN} = 0.8V–2.0V, V _{CC} = 3.0V	0	10	ns/V

Note 3: Absolute Maximum continuous ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute maximum rated conditions is not implied.

Note 4: I_O Absolute Maximum Rating must be observed.

DC Electrical Characteristics

Symbol	Parameter		V _{CC}	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		Units	Conditions	
Symbol	Paramete	er	(V)	Min	Max	Units	Conditions	
V _{IK}	Input Clamp Diode Voltage		2.7		-1.2	V	I _I = -18 mA	
V _{IH}	Input HIGH Voltage		2.7-3.6	2.0		V	$V_0 \le 0.1V$ or	
V _{IL}	Input LOW Voltage		2.7-3.6		0.8	V	$V_O \ge V_{CC} - 0.1V$	
V _{OH}	Output HIGH Voltage		2.7-3.6	V _{CC} -0.2		V	$I_{OH} = -100 \mu A$	
			3.0	2.0		V	$I_{OH} = -12 \text{ mA}$	
V _{OL}	Output LOW Voltage		2.7		0.2	V	$I_{OL} = 100 \mu A$	
			3.0		0.8	V	I _{OL} = 12 mA	
I _{I(HOLD)}	Bushold Input Minimum Drive)	3.0	75		μА	$V_I = 0.8V$	
(Note 5)			3.0	-75		μА	$V_I = 2.0V$	
I _{I(OD)}	Bushold Input Over-Drive		3.0	500		μА	(Note 6)	
(Note 5)	Current to Change State	hange State		-500		μА	(Note 7)	
l _I	Input Current		3.6		10		$V_I = 5.5V$	
		Control Pins	3.6		±1	μА	$V_I = 0V$ or V_{CC}	
		Data Pins	3.6		-5	μА	$V_I = 0V$	
	Dat	Data Filis	3.0		1		$V_I = V_{CC}$	
I _{OFF}	Power Off Leakage Current	•	0		±100	μΑ	$0V \le V_I \text{ or } V_O \le 5.5V$	
I _{PU/PD}	Power Up/Down		0-1.5V		±100	μА	V _O = 0.5V to 3.0V	
	3-STATE Current		0-1.50		±100	μА	$V_I = GND \text{ or } V_{CC}$	
l _{OZL}	3-STATE Output Leakage Cu	rrent	3.6		-5	μΑ	V _O = 0.5V	
l _{ozh}	3-STATE Output Leakage Cu	rrent	3.6		5	μΑ	V _O = 3.0V	
l _{ozh} +	3-STATE Output Leakage Current		3.6		10	μА	$V_{CC} < V_O \le 5.5 V$	
ссн	Power Supply Current		3.6		0.19	mA	Outputs HIGH	
I _{CCL}	Power Supply Current		3.6		5	mA	Outputs LOW	
I _{CCZ}	Power Supply Current		3.6		0.19	mA	Outputs Disabled	

DC Electrical Characteristics (Continued)

Symbol	Parameter	v _{cc}	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$		Units	Conditions	
Cynnbon	T didileter	(V)	Min	Max	Oilles	Containons	
I _{CCZ} +	Power Supply Current	3.6		0.19	mA	$V_{CC} \le V_O \le 5.5V$, Outputs Disabled	
Δl _{CC}	Increase in Power Supply Current (Note 8)	3.6		0.2	mA	One Input at V _{CC} – 0.6V Other Inputs at V _{CC} or GND	

Note 5: Applies to bushold versions only (74LVTH162244).

Note 6: An external driver must source at least the specified current to switch from LOW-to-HIGH.

Note 7: An external driver must sink at least the specified current to switch from HIGH-to-LOW.

Note 8: This is the increase in supply current for each input that is at the specified voltage level rather than V_{CC} or GND.

Dynamic Switching Characteristics (Note 9)

Symbol Parameter		v _{cc}	T _A = 25°C		Units	Conditions		
Cymbol	i arameter	(V) Min Typ		Тур	Max		$\textbf{C}_{\textbf{L}} = \textbf{50}~\text{pF,}~\textbf{R}_{\textbf{L}} = \textbf{500}\Omega$	
V _{OLP}	Quiet Output Maximum Dynamic V _{OL}	3.3		0.8		V	(Note 10)	
V _{OLV}	Quiet Output Minimum Dynamic V _{OL}	3.3		-0.8		V	(Note 10)	

Note 9: Characterized in SSOP package. Guaranteed parameter, but not tested.

Note 10: Max number of outputs defined as (n). n-1 data inputs are driven 0V to 3V. Output under test held LOW.

AC Electrical Characteristics

-		T _A = -	$T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, $C_L = 50$ pF, $R_L = 500\Omega$					
Symbol	Parameter	V _{CC} = 3.	3V ± 0.3V	V _{CC}	Units			
		Min	Max	Min	Max	Onits		
t _{PLH}	Propagation Delay Data to Output	1.4	4.0	1.4	4.8			
t _{PHL}		1.2	3.7	1.2	4.1	ns		
t _{PZH}	Output Enable Time	1.2	5.1	1.2	6.5	ns		
t_{PZL}		1.4	5.4	1.4	6.9	115		
t _{PHZ}	Output Disable Time	2.0	5.0	2.0	5.4	ns		
t_{PLZ}		1.5	5.0	1.5	5.4	115		
t _{OSHL}	Output to Output Skew		1.0		1.0	ns		
toslh	(Note 11)		1.0		1.0	115		

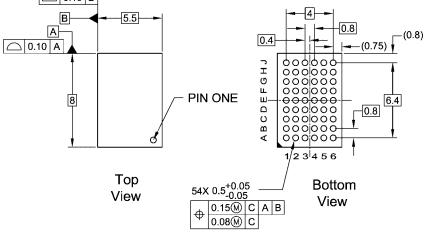
Note 11: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}).

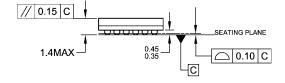
Capacitance (Note 12)

Symbol	Parameter	Conditions	Typical	Units
C _{IN}	Input Capacitance	$V_{CC} = 0V$, $V_I = 0V$ or V_{CC}	4	pF
C _{OUT}	Output Capacitance	$V_{CC} = 3.0V$, $V_{O} = 0V$ or V_{CC}	8	pF

Note 12: Capacitance is measured at frequency f = 1 MHz, per MIL-STD-883, Method 3012.

Physical Dimensions inches (millimeters) unless otherwise noted ○ 0.10 B В



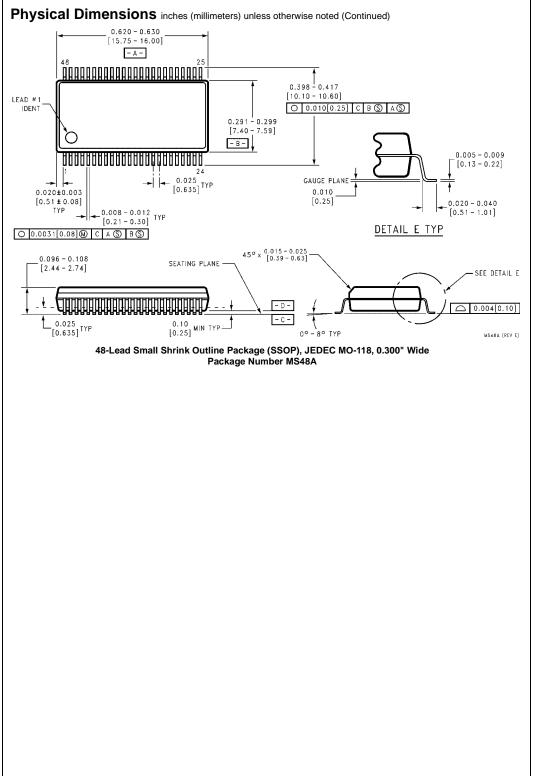


NOTES:

- A. THIS PACKAGE CONFORMS TO JEDEC M0-205
- **B. ALL DIMENSIONS IN MILLIMETERS**
- C. LAND PATTERN RECOMMENDATION: NSMD (Non Solder Mask Defined)
 .35MM DIA PADS WITH A SOLDERMASK OPENING OF .45MM CONCENTRIC TO PADS
 D. DRAWING CONFORMS TO ASME Y14.5M-1994

BGA54ArevD

54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide Package Number BGA54A



Resistors in the Outputs

Physical Dimensions inches (millimeters) unless otherwise noted (Continued) 12.50±0.10 0.40 TYP -B-99. 9.20 8.10 50. O.2 C B A ALL LEAD TIPS PIN #1 IDENT 0.50 LAND PATTERN RECOMMENDATION 0.1 C SEE DETAIL A 0.90+0.15 0.09-0.20 0.10±0.05 0.17-0.27 0.50 ♦ 0.13@ A BS CS 12.00' TOP & BOTTOM DIMENSIONS ARE IN MILLIMETERS R0.16 GAGE PLANE 0.25 NOTES: A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION ED, DATE 4/97. B. DIMENSIONS ARE IN MILLIMETERS. SEATING PLANE 0.60±0.10 1.00 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS. D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982. DETAIL A

48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide Package Number MTD48

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MTD48REVC

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